

# DSK5J01

## Silicon N-channel Junction FET

For low frequency amplification

For pyroelectric sensor

### ■ Features

- High gate-drain voltage (source open)  $V_{GDO}$
- Contributes to miniaturization of sets, reduction of component count.
- Eco-friendly Halogen-free package

### ■ Packaging

Embossed type (Thermo-compression sealing): 3000 pcs / reel (standard)

### ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Gate-drain breakdown voltage	$V_{GDS}$	-55	V
Drain current	$I_D$	30	mA
Gate current	$I_G$	10	mA
Power dissipation	$P_D$	150	mW
Channel temperature	$T_{ch}$	150	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-55 to +150	$^\circ\text{C}$

### ■ Package

- Code  
SMini3-F2-B
- Pin Name  
1: Source  
2: Drain  
3: Gate

### ■ Marking Symbol: B6

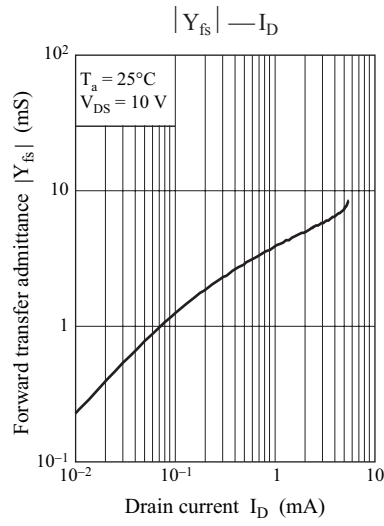
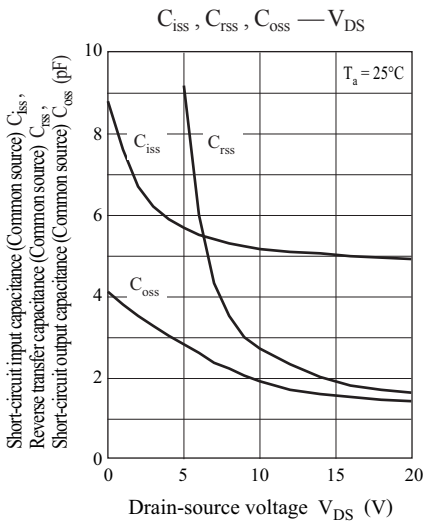
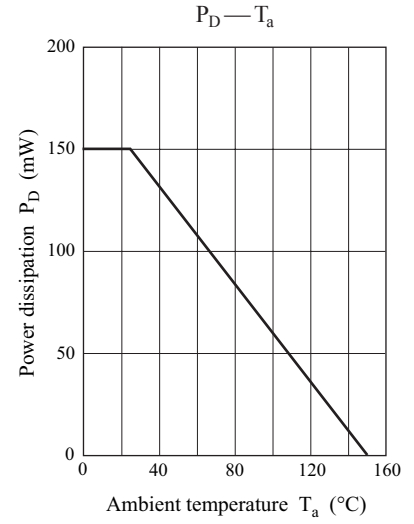
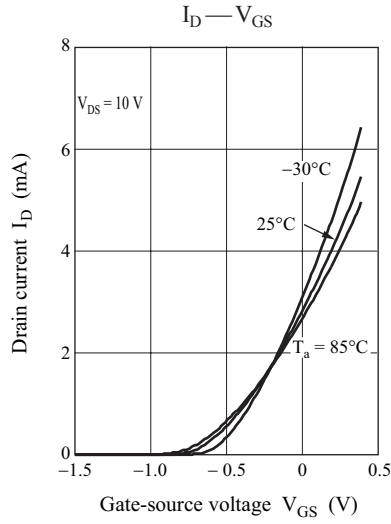
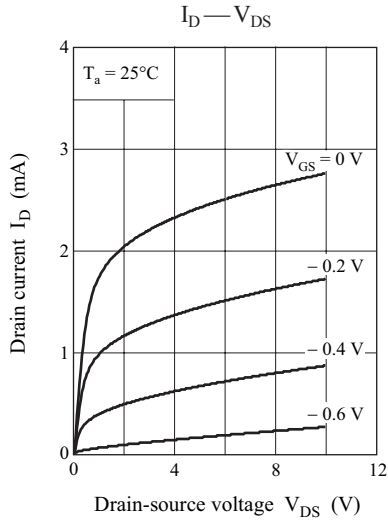
### ■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Gate-drain breakdown voltage	$V_{GDS}$	$I_G = -100 \mu\text{A}, V_{DS} = 0$	-55			V
Drain-source cutoff current *	$I_{DSS}$	$V_{DS} = 10 \text{ V}, V_{GS} = 0$	1.0		12.0	mA
Gate-source cutoff current	$I_{GSS}$	$V_{GS} = -30 \text{ V}, V_{DS} = 0$			-10	nA
Gate-source cutoff voltage	$V_{GSC}$	$V_{DS} = 10 \text{ V}, I_D = 10 \mu\text{A}$			-5	V
Forward transfer admittance	$ Y_{fs} $	$V_{DS} = 10 \text{ V}, I_D = 5 \text{ mA}, f = 1 \text{ MHz}$	2.5	7.5		mS
Short-circuit input capacitance (Common source)	$C_{iss}$	$V_{DS} = 10 \text{ V}, V_{GS} = 0, f = 1 \text{ MHz}$		6.0		pF
Reverse transfer capacitance (Common source)	$C_{rss}$			2.5		pF

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

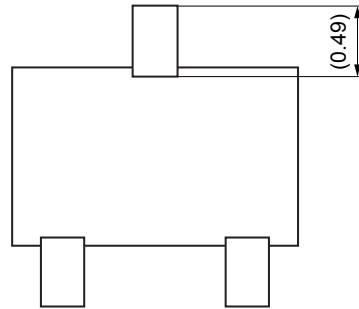
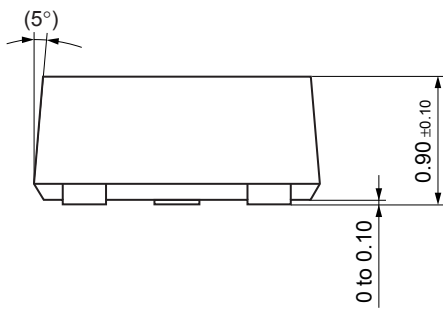
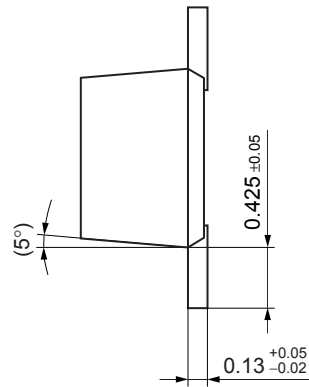
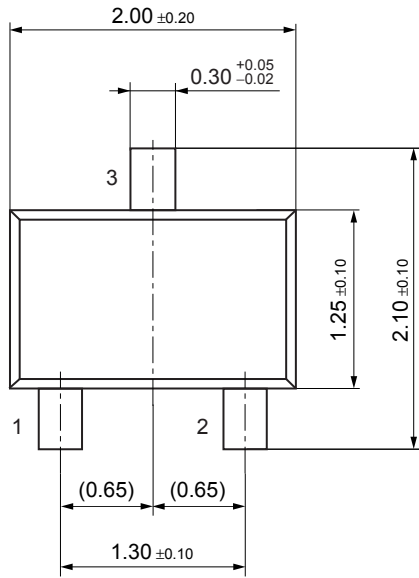
2. \*: Rank classification

Code	P	Q	R
Rank	P	Q	R
$I_{DSS}$	1.0 to 3.0	2.0 to 6.5	5.0 to 12.0
Marking Symbol	B6P	B6Q	B6R



SMini3-F2-B

Unit: mm



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